

ISO-9001-2015 Certified

TECHNICAL BULLETIN

EPOXIBOND™ EB-350-1LE ONE COMPONENT EPOXY ADHESIVE & ENCAPSULANT

EB-350-1LE is a high performance, single component, epoxy encapsulant which cures on exposure to heat. The product has a high viscosity and excellent viscosity stability. These characteristics make it ideal for encapsulating devices *without* the need for a physical barrier. The product is formulated specifically to pass 1000 hours of temperature/humidity/bias testing and thermal cycling up to 125°C.

EB-350-1LE-T is a thixotropic version where high viscosity & control flow required.

TYPICAL APPLICATIONS

- Chip-on-Board (COB) encapsulation
- > Encapsulation of surface mounted devices to printed circuit boards
- Particularly suited for semiconductors (Transistors, Smart Cards, watch ICs) where potting indentations are not provided.

TYPICAL HANDLING PROPERTIES:

| Consistency | Paste |
|---------------------------|-----------------------|
| Pot life at 80°C, minutes | 20 |
| | |
| Shelf life | 4 months @ 25°C |
| | 6 months @ below 10°C |
| | |
| Recommended Cure | 30 min @ 150°C |
| Alternate Cure | 2 hrs @ 125°C |

TYPICAL CURED PROPERTIES:

| Color | Black | |
|---|--------------|--|
| Specific Gravity | 1.60 | |
| Hardness, Shore D | 91 | |
| Water Absorption (24 hrs at 25°C), % | 0.09 | |
| Lap Shear Strength to Aluminum, psi | | |
| At 25°C | 2400 | |
| At 100°C | 1800 | |
| Thermal Conductivity, W/m°K | 0.5 | |
| Flexural Strength, psi | 12,400 | |
| Flexural Modulus, psi | $1x10^{6}$ | |
| Service Temperature range, °C | -55 to 175 | |
| Glass Transition Temperature, °C | 120 | |
| Coefficient of Linear Thermal Expansion, 10 ^{-6/°} C | | |
| Below Tg | 28 | |
| Above Tg | 110 | |
| Dielectric Constant at 1 kHz | 3.8 | |
| Dissipation Factor at 1 kHz | 0.01 | |
| Volume Resistivity, ohm-cm | $>1x10^{15}$ | |
| | | |

INSTRUCTIONS FOR USE:

- 1. Use dispensing equipment for best results.
- 2. For small applications, apply the product using a syringe or clean spatula.
- 3. Avoid air entrapment to obtain optimum cured properties.
- 4. Proceed with the bonding or potting application and cure as recommended.

<u>CAUTION:</u> May exotherm violently in excess of 0.5 inches thick or more than 50 grams for potting or encapsulating applications.

FOR INDUSTRIAL USE ONLY:

This material is intended for industrial use only, and the practices of good housekeeping, safety and cleanliness should be followed before, during and after use.

WARNING!

Although the system contains low volatility materials, care should be taken in handling. Adequate ventilation of work place and ovens is essential. Refer to Material Safety Data Sheet for additional health and safety information.

SHELF LIFE:

The shelf life of this material is over 4 months when stored in unopened containers below 10° C temperature. Storage at 0° C to 5° C will improve the shelf life of the product.

DISCLAIMER: All data given here is offered as a guide to the use of these materials and not as a guarantee of their performance. The user should evaluate their suitability for own purposes. Properties are typical and should not be used in preparing specifications. Statements are not to be construed as recommendations to infringe any patent.